

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	("4862322" "5074947" "5214250" "5267867" "5290970" "5367593" "5382545" "5579574" "5627406" "5700737" "5841193" "5918364" "5972152" "5998738" "6103554" "6138348" "6141245" "6174804" "6246010" "6246010" "6372549" "6372549" "6515870" "6515870" "6528891" "6528891" "6664176" "6846737" "6846737").PN. and (circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat\$4 or thermal\$4) and (clean\$4 or ash\$4) and cool\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:06
L2	543	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat\$4 or thermal\$4) and (clean\$4 or ash\$4) and cool\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:08
L3	73	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat\$4 or thermal\$4) and (clean\$4 or ash\$4) and cool\$4 and defect\$4 and stud	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:08
L4	73	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat\$4 or thermal\$4) and (clean\$4 or ash\$4) and cool\$4 and defect\$4 and stud and bond	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:09
L5	8	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat\$4 or thermal\$4) and (clean\$4 or ash\$4) and cool\$4 and defect\$4 and stud and bond and (438/106.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:10

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L6	8	(circuit or device or semiconductor) and (substrate or wafer or base or carrier) and bump and (solder near9 well) and bond and (heat\$4 or thermal\$4) and (clean\$4 or ash\$4 or wash\$4) and cool\$4 and defect\$4 and stud and bond and (438/106. ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:11
S1	346	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat\$4 or oxide) and (interconnect\$4 near4 circuit) and (I/O near4 pad) and wells and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/19 13:04
S2	24	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat\$4 or oxide) and (interconnect\$4 near4 circuit) and ((I/O near4 pad) near8 wells) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 11:09
S3	0	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat\$4 or oxide) and (interconnect\$4 near4 circuit) and ((I/O near4 pad) near8 wells) and solder and squeegee	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:49
S4	8	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat\$4 or oxide) and (interconnect\$4 near4 circuit) and ((I/O near4 pad) near8 wells) and solder and squeegee	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:49
S5	1	(glass near4 (substrate or semiconductor or wafer or carrier)) near8 (dielectric or insulat\$4 or oxide) and (interconnect\$4 near4 circuit) and ((I/O near4 pad) near8 wells) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 10:56
S6	7	(substrate or semiconductor or wafer or carrier) near8 (dielectric or insulat\$4 or oxide) and (interconnect\$4 near4 circuit) and ((I/O near4 pad) near8 wells) and ((conductive or metal or solder) near4 bond)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:33

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S7	17	"6141245"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:37
S8	5719	trace near4 rout\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:37
S9	1357	(trace near4 rout\$4) and (interconnect\$4 near4 circuit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:38
S10	55	(trace near4 rout\$4) and (multiple near4 (interconnect\$4 near4 circuit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:39
S11	5	(trace near4 rout\$4) and (multiple near4 (interconnect\$4 near4 circuit)) and level near4 contact	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:49
S12	0	("5214250" "5267867" "5290970" "5579574" "5627406" "5972152" "5998738" "6103554" "6141245" "6246010" "6372549" "6515870" "6528891" "6664176" "6846737").PN. and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:51
S13	2	("5214250" "5267867" "5290970" "5579574" "5627406" "5972152" "5998738" "6103554" "6141245" "6246010" "6372549" "6515870" "6528891" "6664176" "6846737").PN. and S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/25 12:51